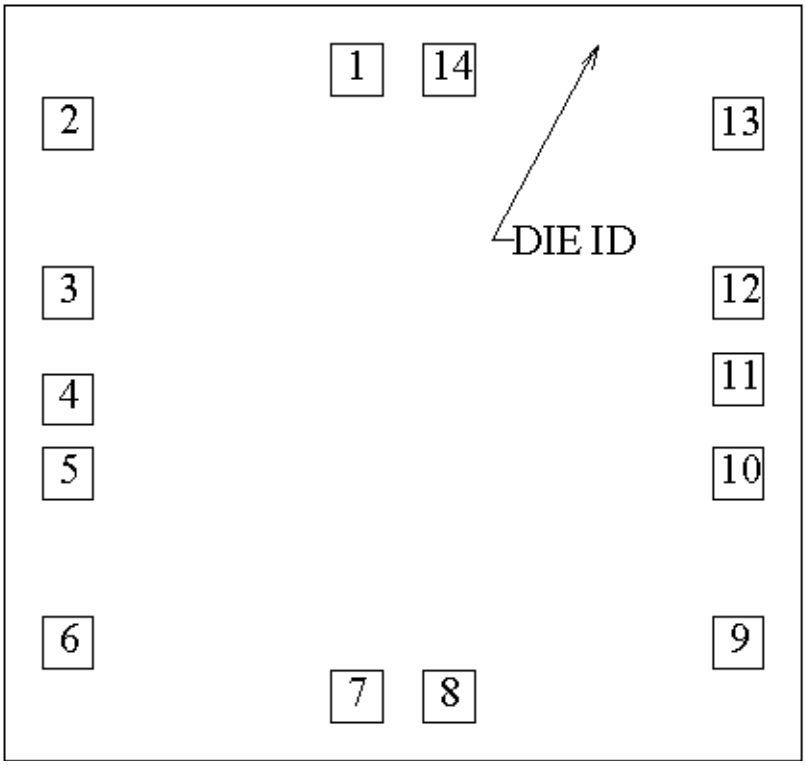
LM124 MDS
LOW POWER QUAD OPERATIONAL AMPLIFIER

July 06,2004

DIE LAYOUT (H-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	1902H	Bond Pad Opening Size (min)	92μm x 92μm
Die Step	H	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1422μm x 1346μm 56.0mils x 53.0mils	Back Side Connection	Floating or GND
Thickness	330μm Nominal		
Min Pitch	127μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (H -Step)

(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Output 1	1	-82	559	92	x	92
Input 1-	2	-597	461	92	x	92
Input 1+	3	-597	161	92	x	92
V+	4	-597	-29	92	x	92
Input 2+	5	-597	-161	92	x	92
Input 2-	6	-597	-461	92	x	92
Output 2	7	-82	-559	92	x	92
Output 3	8	82	-559	92	x	92
Input 3-	9	597	-461	92	x	92
Input 3+	10	597	-161	92	x	92
Gnd	11	597	7	92	x	92
Input 4+	12	597	161	92	x	92
Input 4-	13	597	461	92	x	92
Output 4	14	82	559	92	x	92

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